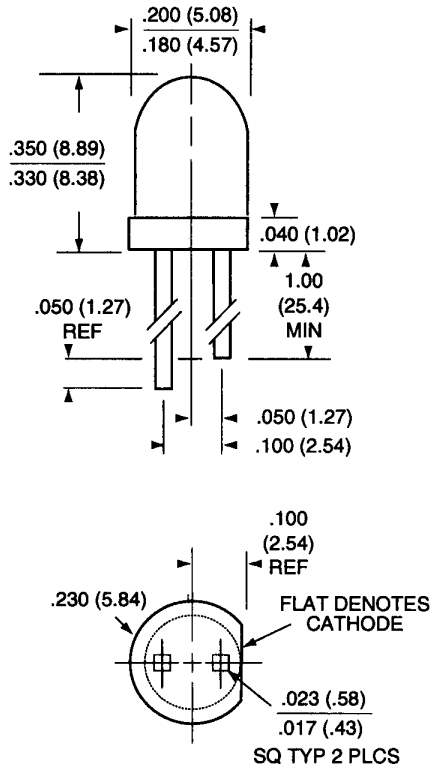


### PACKAGE DIMENSIONS



- Note: 1) All dimensions are in inches (mm).  
 2) Lead spacing is measured where the leads emerge from the package.  
 3) Protruded resin under the flange is 0.059" (1.5mm) max.  
 4) All tolerances are  $\pm 0.010$ " (0.25mm) unless otherwise noted.

### DESCRIPTION

This T-1 3/4 white LED has a water clear lens and provides a viewing angle of 20°. It utilizes a GaN or InGaN blue LED chip with a phosphorous powder coating to produce the white light.

### FEATURES

- Popular T-1 3/4 package
- Fluorescent light emission
- Standard 100 mil. lead spacing
- Emission color:  
 $X = 0.31$   
 $Y = 0.32$

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise specified)

DC Forward Current (I <sub>F</sub> )	30 mA
Peak Forward Current (I <sub>F</sub> ) @ f = 100Hz, Duty factor = 1/10	100 mA
Power Dissipation (P <sub>d</sub> )	120 mW
Operating Temperature Range	-30°C to +80°C
Storage Temperature Range	-40°C to +100°C
Lead Soldering Time (1/16" from body)	3 secs @ 260°C

#### ELECTRO-OPTICAL CHARACTERISTICS (T<sub>A</sub>=25°C unless otherwise specified)

Part Number:	MV8W00	Test Condition
Luminous Intensity (mcd) <i>Testing Condition @ 550nm</i>		I <sub>F</sub> = 20 mA
Minimum	1300	
Typical	2500	
Forward Voltage (V)		I <sub>F</sub> = 20 mA
Typical	3.8	
Maximum	5.0	
Peak Wavelength (nm)	550	I <sub>F</sub> = 20 mA
Chromaticity Coordinates		I <sub>F</sub> = 10 mA
Typical	X = 0.31 Y = 0.32	
Reverse Breakdown Voltage (V)	5	I <sub>R</sub> = 10 μA
Viewing Angle (Deg.)	20	I <sub>F</sub> = 20 mA

#### TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES (T<sub>A</sub> = 25°C)

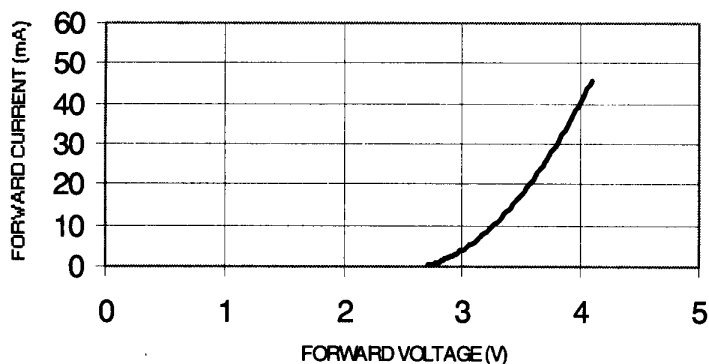


Fig 1. Forward Voltage vs. Forward Current

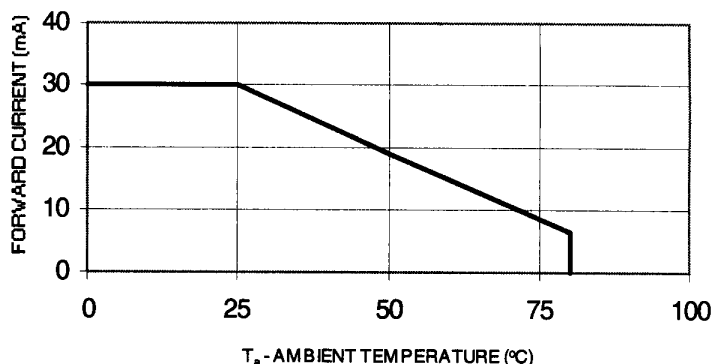


Fig 2. Forward Current vs. Ambient Temperature

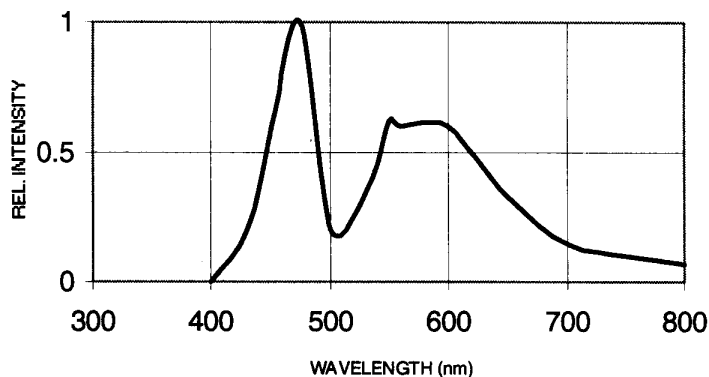


Fig 3. Rel. Intensity vs. Wavelength

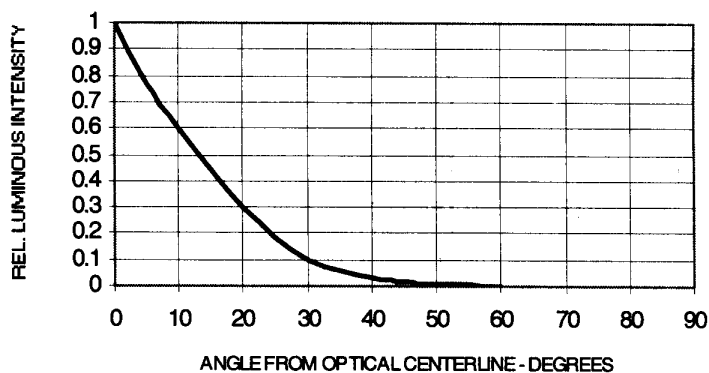


Fig 4. Rel. Intensity vs. Angular Displacement

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